



*i*SPAN[®] 3639 AdvancedMC[™] T1/E1/J1 Communications Controller

Quad/Octal Port Multiprotocol Controller for Signaling and Media Applications on AdvancedTCA and µTCA Platforms

FEATURES

Four or Eight T1/E1/J1 interfaces

Optimized for Signaling and Media applications

Designed for ATCA and μTCA platforms

Rich and field-proven Software Development Suite (*i*WARE)

On-board support for multiple network protocols:

- SS7 (MTP1 & MTP2) LSL/HSL
- SAAL/GR-2878
- ATM (incl. IMA)
- Frame Relay
- HDLC & Media Interface
- I-TDM

Pre-integrated with various 3rd party upper layer protocol stacks

Single width, Mid-size or Full-size PICMG AMC.0 R2.0 compliant

Front or Rear access

Optional acceleration of media termination and circuit switching*

Freescale[™] MPC8560 (PowerQUICC III[™]) on-board processor @ 833 MHz

PCI-Express (AMC.1) and Gigabit Ethernet (AMC.2) connectivity

Support of telecom clocks TCLKA, TCLKB, TCLKC and TCLKD.

APPLICATIONS

Softswitches and MSC Servers Serving / Gateway GPRS Support Nodes (xGSNs) Signaling Gateways Wireless BSCs/RNCs Media Gateways Media Servers Call Servers HLRs

Designed for Signaling and Media Applications

The *i*SPAN 3639 AdvancedMC[™] T1/E1/J1 communications controller from Interphase delivers a comprehensive high-capacity connectivity solution for use with AdvancedTCA and MicroTCA platforms to deliver a wide range of Voice-Over-IP, Wireless and IP Multi-Media Subsystem (IMS) infrastructure application elements.

High Performance and Capacity

With up to 8 T1/E1/J1 interfaces, the *i*SPAN 3639 provides a high-capacity solution for signaling and media applications and enables optimization of slot usage. With support for a high-performance PCI-Express interface to a host processor, or gigabit Ethernet connectivity to the AdvancedMC connector, the *i*SPAN 3639 enables rapid exchange of payload information and is hence ideal for a broad spectrum of applications requiring T1/E1/J1 connectivity.

Powerful Solution Architecture

The *i*SPAN 3639 incorporates the Freescale PowerQUICC III^{TM} communications controller to deliver high-performance and high-capacity processing of signaling traffic. With the addition of an optional FPGA-based support for TDM switching* and I-TDM protocol conversion, the 3639 can be used for full capacity media termination and media switching applications.



2/1/10

1 INTERPHASE

3639 Solution Components

AdvancedMC Connectivity

- PCI-Express x1 link on AMC port 4 (AMC.1 Type 1)
- 2 Gigabit Ethernet links on AMC port 0 (AMC.2 Type E1) and 8 (AMC.2 T1)
- Optional I-TDM Gigabit Ethernet link on AMC port 1 or 9
- Telecom clocks on TCLKA and TCLKB, optionally TCLKC/D
- PCI-Express 100 MHz clock input on AMC FCLKA
- T1/E1/J1 line signals on AMC port 20-12 towards 3rd-party Rear Transition Module

Processor/Memory

- PowerQUICC III (MPC8560) RISC processor, allowing full support of various communication protocols, and reducing host CPU processing
- · Optional FPGA-based media termination and switching
- 128 MB of DDR SDRAM on SODIMM (up to 1GB)
- Optional SDRAM for CPM tables (best CPM performances)
- 16 MB downloadable 8-bit Flash Memory
- Option for up to 256 MB of NAND Flash

Network Interfaces

The 3639 can interface with PSTN/ISDN networks via:

- Four or eight individually software selectable T1/E1/J1 lines
 - o Front access, on 4 RJ45 connectors, each supporting 2 lines, or
 - o Rear access, on AMC ports 20 to 12
 - QuadFALC[™] framers supporting long or short haul interfaces, AMI, HDB3, or B8ZS line coding and various superframe formats
- I-TDM over a Gigabit Ethernet link on AMC connector (line interfaces are located on another card in the system)

Telecom Clock Management

- Line interfaces configurable in LT (clock slave) or NT (clock master) mode (lines can have independent clock rhythms)
- Three synchronization modes supported:
 - o Free running internal clock
 - Recovered clock (loop back timing) from any T1/E1/J1 line
 - System telecom clock reference (via AMC TCLKA or TCLKC)
- Clock can be forwarded to AMC TCLKB or TCLKD

Board Development Kit

The 3639 BDK is specific to the 3639 hardware and not tied to a particular operating system environment. The kit contains the following main components:

- Boot Firmware with power-on self-test, power-on boot sequence, built-in selftest and configuration via a command line interface
- Setup and Built-in Self-test utilities, Documentation

Board Support Package

The 3639 Linux BSP provides kernel, development environment and basic drivers for use with Linux to develop embedded software on the 3639.

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WARE[®] Software Development Suite (SDS)

The *i*WARE SDS is an integrated set of embedded firmware, host drivers and utilities that accelerates application development and eases integration of the *i*SPAN 3639 to deliver end applications. Protocols provided:

- SS7 MTP1 and 2 (up to 128 LSLs)
- ATM AAL0, AAL2, and AAL5, with IMA capability
- SSCF and SSCOP (SAAL)
- Frame Relay
- HDLC and Enhanced Media transfers (HMP applications)*
- I-TDM for media transport over Ethernet backplane

*i*WARE SDS provides the same API in PCI-Express and Ethernet modes.

Application Example: The iSPAN 3639 provides the PSTN interface to a μ TCA VoIP Access Gateway (1K media channels with embedded Signaling Gateway):



Technical Specifications

Architecture

Processor RAM Memory ROM Memory Connectivity

Mechanical Form Factor

Length Width

Operating Environment Power Consumption

 Temperature
 0 to 55 °C (32

 Storage Range
 -40 to 80 °C (

 Relative Humidity
 5% to 95% no

 Altitude
 0 to 15.000 ft

MPC8560 @ 833 MHz 128 MB DDR SDRAM or SODIMM 16 MB NOR Flash, 128 MB NAND Flash AMC.1 (PCI Express), AMC.2 (Ethernet)

AdvancedMC single-width Full/Mid-size 180.6 mm (7.11 in.) 73.5 mm (2.89 in.) (single-width)

20 W typ. / 24 W max. 0 to 55 °C (32 to 131 °F) -40 to 80 °C (-40 to 176 °F) 5% to 95% non-condensing

About Interphase Corporation

Interphase Corporation (NASDAQ: INPH) delivers solutions for network connectivity, interworking, and packet processing for key applications for the communications, Mil/Aero, and enterprise markets. Founded in 1974, Interphase provides expert customization services and contract manufacturing, in addition to its COTS portfolio, and plays a leadership role in next generation AdvancedTCA® (ATCA), AdvancedMCTM (AMC), PCI-X, and PCIe standards and solutions. Interphase is headquartered in Plano, Texas, with sales offices across the globe.